HOSTAFORM® S 9362

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Hostaform® acetal copolymer grade S 9362 is an impact modified grade for applications requiring improved impact. Hostaform® S 9362 provides good impact strength while improving modulus and weld line strength over standard impact modified grades. Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM-HI		ISO 1043
Part Marking Code	>POM-HI<		ISO 11469

Rheological properties

Melt volume-flow rate	6.5	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Molding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	334000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	8000	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	10	%	ISO 527-1/-2
Flexural modulus	319000	psi	ISO 178
Charpy impact strength, 23°C	N	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	90.4	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	4.76	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	2.85	$ftlb/in^2$	ISO 179/1eA
Izod notched impact strength, 23°C	4.76	$ftlb/in^2$	ISO 180/1A
Izod notched impact strength, -40°C	2.85	$ftlb/in^2$	ISO 180/1A
Hardness, Rockwell, M-scale	75		ISO 2039-2

Thermal properties

Melting temperature, 10°C/min	329	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	189	°F	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	304	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.61	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.611	E-4/°F	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.25	%	Sim. to ISO 62
Water absorption, 2mm	0.8	%	Sim. to ISO 62
Density	0.0502	lb/in^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	383	°F

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Min. melt temperature	356	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s
Back pressure	290	psi
Ejection temperature	271	°F

Characteristics

Processing	Injection Molding, Extrusion
Additives	Release agent
Special characteristics	High impact or impact modified

Additional information

Processing Notes

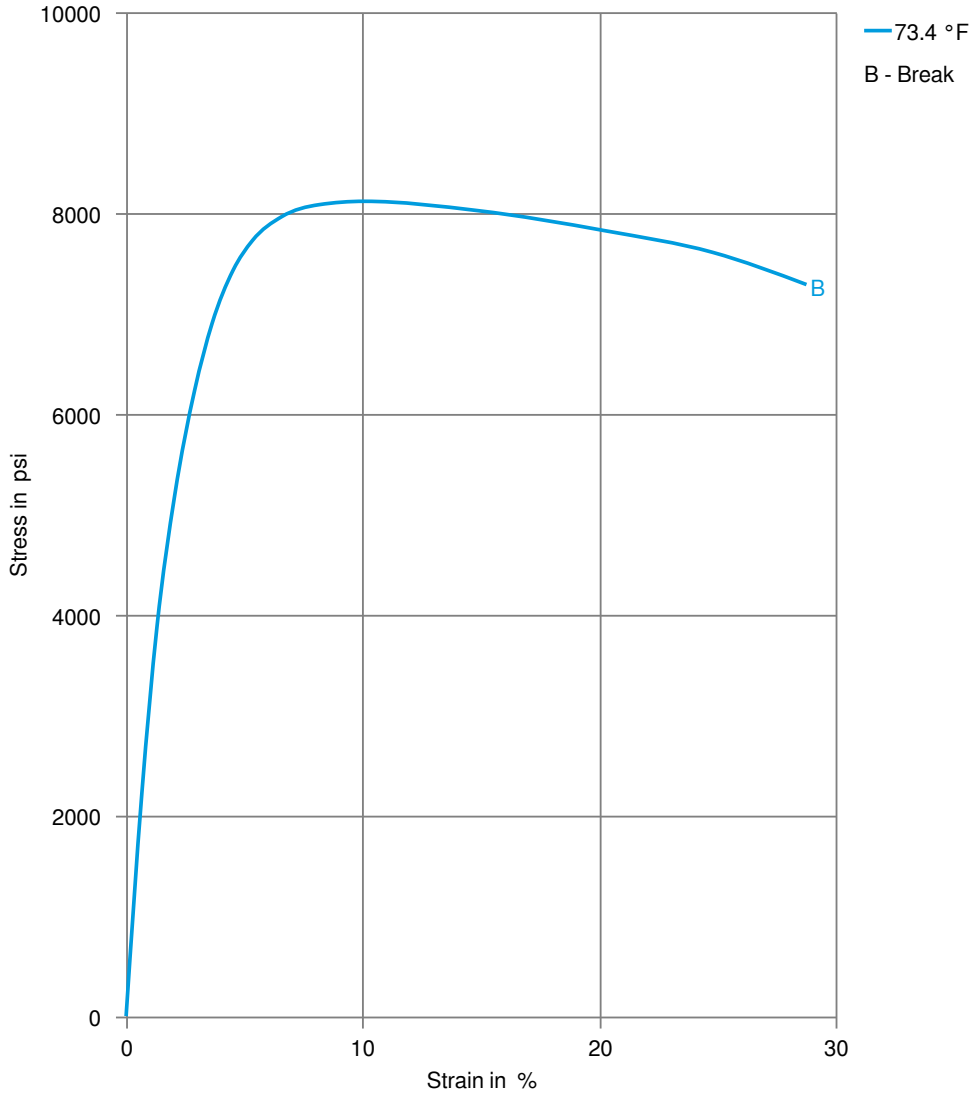
Pre-Drying

Drying is not normally required. If material has contacted moisture through improper storage and handling or through regrind use, dry to prevent splay and odor problems.

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Stress-strain

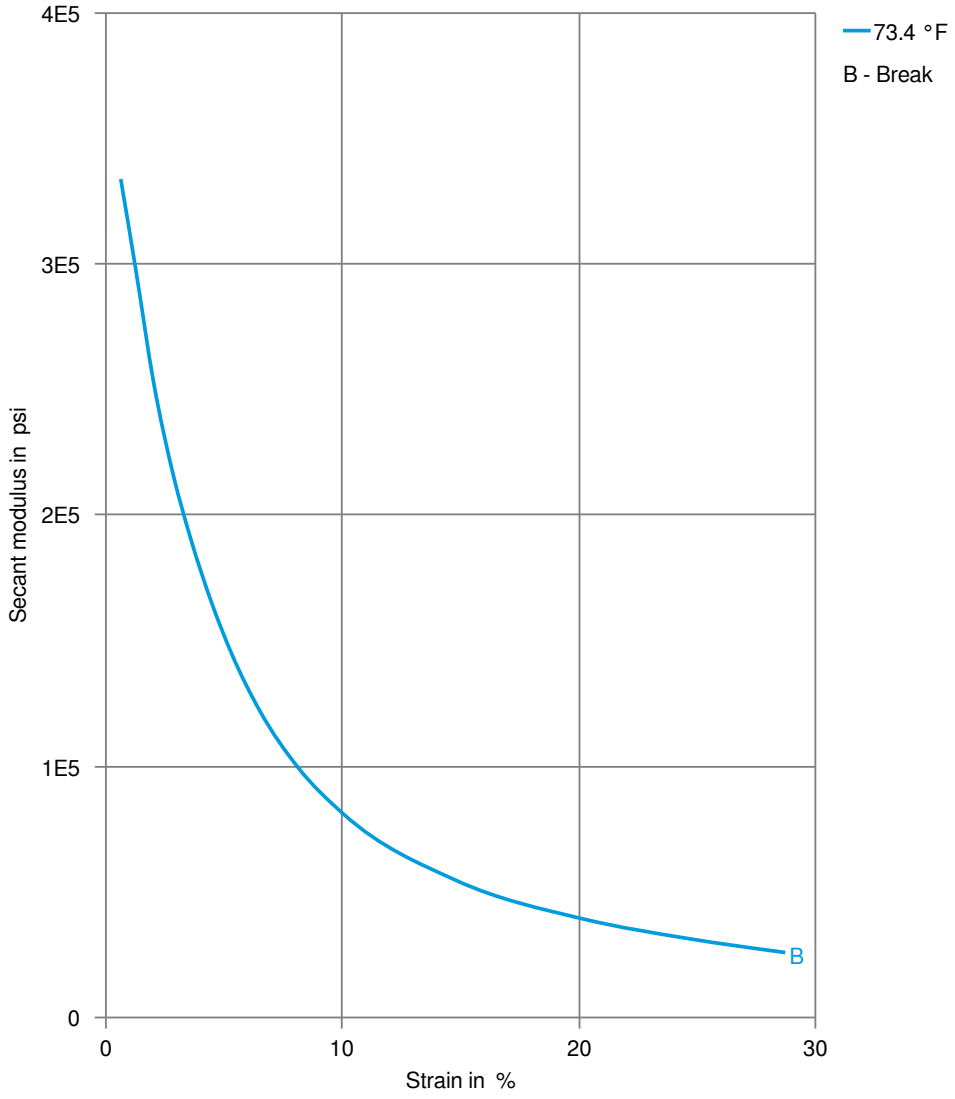


Revised: 2025-07-25 Source: Celanese Materials Database

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Secant modulus-strain



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